

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc1625cgn#trpbf

(Engineering Calculation)

SSOP

(printed on: 2020-07-11 19:02:27)

**TOTAL MASS (g) : 0.083054**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003959	1000000	47667.7421875		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.029933	975000	360403.75		
		Iron (Fe)	7439-89-6	0.000737	24000	8873.73730469		
		Phosphorus (P)	7723-14-0	0.000009	300	108.363143921		
		Zinc (Zn)	7440-66-6	0.000021	700	252.847320557		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.030700</b>	<b>1000000</b>	<b>369638.71875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.002272	1000000	27356.6367188		
		<b>External Plating Total:</b>				<b>0.002272</b>	<b>1000000</b>	<b>27356.6367188</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000246	1000000	2961.92602539		
<b>Internal Plating Total:</b>				<b>0.000246</b>	<b>1000000</b>	<b>2961.92602539</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001101	750000	13256.4238281		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000367	250000	4418.80810547		
<b>Die Attach Total:</b>				<b>0.001468</b>	<b>1000000</b>	<b>17675.2324219</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.006623	150000	79743.2265625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.036203	820000	435896.75		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.001104	25000	13292.5458984		
		Carbon Black (C)	1333-86-4	0.000221	5000	2660.91699219		
		<b>Encapsulation Total:</b>				<b>0.044151</b>	<b>1000000</b>	<b>531593.4375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000258	1000000	3106.40966797		
					<b>TOTAL MASS (g) :</b>	<b>0.083054</b>		